

描述 / Descriptions

SOP-8 塑封封装双 P 沟道 MOS 场效应管。Dual P-Channel MOSFET in a SOP-8 Plastic Package.

特征 / Features

超高密度设计,导通电阻小,可靠性好。

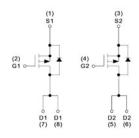
Super high dense cell design for low R_{DS(ON)},Rugged and reliable.

用途 / Applications

用于电源管理,便携式设备和电池供电系统。

Power Management in Notebook computer, Portable Equipment and Battery powered systems.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1: S1 PIN 2: G1 PIN 3: S2 PIN 4: G2



极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数	符号	数值	单位	
Parameter	Symbol	Rating	Unit	
Drain-Source Voltage	V_{DSS}	-20	V	
Gate-Source Voltage	V_{GSS}	±12	V	
Continuous Drain Current	I _D *	-3.0	А	
Pulsed Drain Current	I _{DM} *	-12	А	
Diode Continuous Forward Current	l _s *	-2.0	А	
Power Dissipation for Single Operation	P _D * (Ta=25℃)	2	W	
Power Dissipation for Single Operation	P _D * (Ta=100℃)	0.8	W	
Maximum Junction Temperature	T _j	150	$^{\circ}$	
Storage Temperature Range	T _{stg}	-55 ~ 150	$^{\circ}$	
Thermal Resistance-Junction to Ambient	R _{θJA} *	62.5	°C/W	

Note:

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol		式条件 onditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V	I _{DS} =-250μA	-20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-16V	V _{GS} =0V			-1	μA
		V _{DS} =-16V T _J =85°C	V _{GS} =0V			-10	
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =VGS	I _{DS} =-250μA	-0.50	-0.7	-1.0	V
Gate Leakage Current	I _{GSS}	V _{GS} =±12V	V _{DS} =0V			±100	nA
Drain-Source On-state Resistance	R _{DS(ON)} ^a	V _{GS} =-10V	I _{DS} =-2.7A		75	97	mΩ
		V _{GS} =-4.5V	I _{DS} =-2.7A		82	100	
		V _{GS} =-2.5V	I _{DS} =-2.2A		115	135	
Diode Forward Voltage	V_{SD}^a	V _{GS} =0V	I _{SD} =-1.0A		-0.7	-1.3	V
Total Gate Charge	Q _g ^b	V _{DS} =-6V I _{DS} =-2.7A			3.2	6	nC
Gate-Source Charge	Q _{gs} ^b		V _{GS} =-4.5V		0.65		nC
Gate-Drain Charge	Q _{gd} ^b				1.0		nC

^{*} Surface Mounted on 1in2 pad area, t ≤ 10sec.



电性能参数 / Electrical Characteristics(Ta=25°C)

参数	符号	测试条件	最小值	典型值	最大值	单位
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Gate Resistance	R _G ^b	V_{GS} =0V V_{DS} =0V F =1MHz		6		Ω
Input Capacitance	C _{iss} ^b			325		
Output Capacitance	C _{oss} ^b	V _{GS} =0V V _{DS} =-6V Frequency=1.0MHz		63		pF
Reverse Transfer Capacitance	C _{rss} ^b	, ,		37		
Turn-on Delay Time	t _{d(ON)} b	V_{DD} =-6V R_L =6 Ω I_{DS} =-1A V_{GEN} =-10V R_G =6 Ω		11	22	ns
Turn-on Rise Time	T _r ^b			5.5	11	
Turn-off Delay Time	T _{d(OFF)} b			22	40	
Turn-off Fall Time	T _f ^b			10	20	

Notes:

a : Pulse test ; pulse width≤300µs, duty cycle≤2%.

b : Guaranteed by design, not subject to production testing.



Typical Electrical and Thermal Characteristics

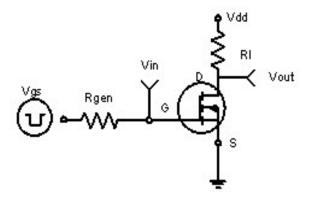


Figure 1:Switching Test Circuit

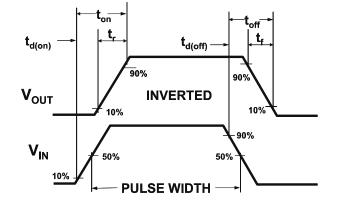
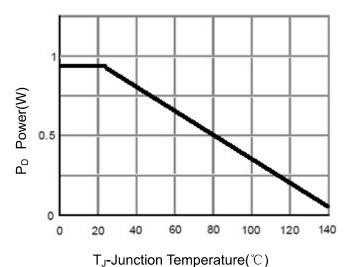


Figure 2:Switching Waveforms



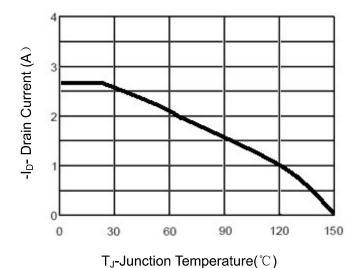


Figure 4 Drain Current



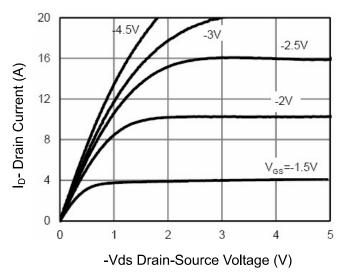


Figure 5 Output Characteristics

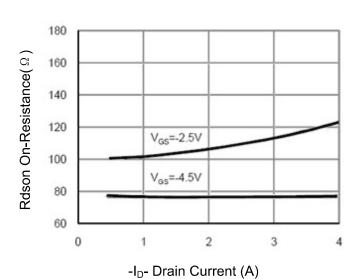


Figure 6 Drain-Source On-Resistance



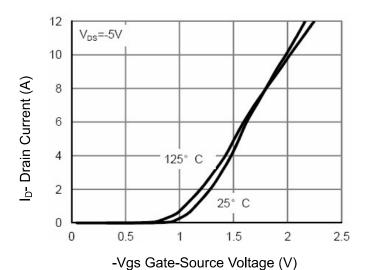


Figure 7 Transfer Characteristics

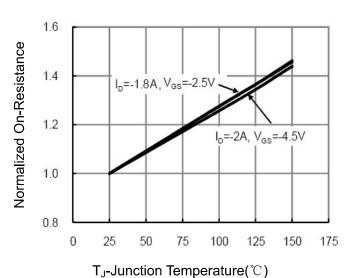


Figure 8 Drain-Source On-Resistance

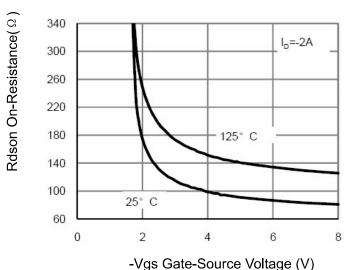


Figure 9 Rdson vs Vgs

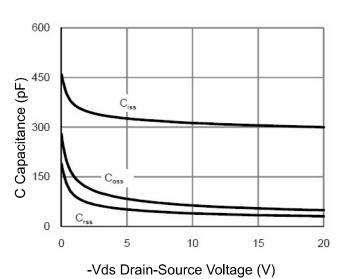


Figure 10 Capacitance vs Vds

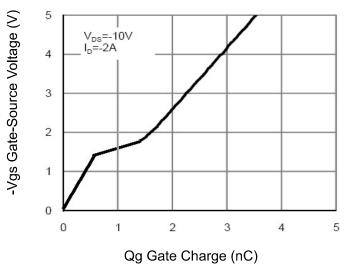


Figure 11 Gate Charge

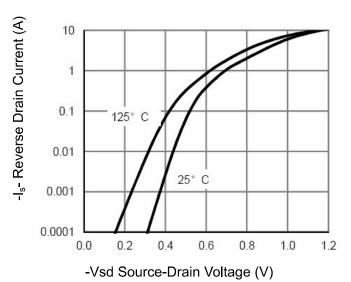


Figure 12 Source- Drain Diode Forward



外形尺寸图 / Package Dimensions

